

Overview

HP ZBook Power G8 Mobile Workstation

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| 1. Ambient Light Sensor | 11. Numeric Keypad |
| 2. Internal Microphones (optional) | 12. Fingerprint Sensor (optional) |
| 3. Camera LEDs (optional) | 13. Touchpad |
| 4. Camera (optional) | 14. Indicator LEDs: Power light, Wireless light, Storage usage light |
| 5. IR Camera (optional) | 15. Power connector |
| 6. Camera Cover | 16. USB Type-CR with Thunderbolt™ 4 |
| 7. Speakers | 17. USB 3.1 Gen 1 |
| 8. Function Keys (changes with configured options) | 18. USB 3.1 Gen 1 |
| 9. Power button | 19. Audio Combo Jack |
| 10. HP Programmable Key | ? ? |
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Overview



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| 1. Nano Security lock slot | 4. HDMI port |
| 2. RJ-45 | 5. Smart Card Reader |
| 3. USB 3.1 Gen 1 Charging Port | ? ? |

At A Glance

- Work anywhere without compromising on performance or security with Windows 10 Pro and HP's collaboration and connectivity technology.
- NVIDIA Quadro GPUs provide the interactive visual workspace you need to do great work wherever, whenever. With twice the CUDA cores as previous generations, NVIDIA Quadro GPUs deliver the performance professionals need to work from anywhere.
- Take multitasking to the next level with 11th gen Intel® Core™ i9 processors built to handle multithreaded apps like Adobe Premiere ProR, and with fast clock speeds to boost your speed on single threaded apps like Autodesk 3ds Max.
- Strenuously tested to meet ISV certification and deliver superb performance and support with leading software providers, including Autodesk and AdobeR.
- Have confidence with HP's most secure mobile workstations and defend against firmware and malware attacks with HP Sure Start and Sure Sense.
- Built with the environment in mind, this ZBook includes recycled ocean-bound plastics, plastic-free packaging, and ultra-efficient power consumption.
- Designed for ultimate durability, this ZBook undergoes brutal MIL-STD 810H tests to help ensure this PC keeps rolling through your workday.
- Plug in to greater connectivity at your desktop with the HP Thunderbolt™ Dock for lightning fast Thunderbolt™ 4 transfers and the flexibility to run up to 1 external 4K and 1 external 5K.
- Work without limits in any location with up to 4TB of local PCIe storage.

NOTE: See important legal disclosures for all listed specs in their respective features sections.

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Features

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OPERATING SYSTEM

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Preinstalled OS Windows 10 Pro 64 - HP recommends Windows 10 Pro for business.¹
Windows 10 Home 64¹
Windows 10 Home Single Language 64¹
FreeDOS

Web support OS Windows 10 Enterprise 64¹

Supported Version HP tested Windows 10, version 1909 on this platform. For testing information on newer versions of Windows, please see: <https://support.hp.com/document/c05195282>.

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¹ Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See <http://www.windows.com>.

² For detailed Linux OS/hardware support information, see: http://www.hp.com/linux_hardware_matrix

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PROCESSOR

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11th Generation Intel® Core™ i9-11950H vPro® with Intel® Iris® Xe Graphics (X.X GHz base frequency, up to X.X GHz with Intel® Turbo Boost Technology, X MB cache, 8 cores)^{1,2,3,4,5,6}

11th Generation Intel® Core™ i9-11900H with Intel® Iris® Xe Graphics (X.X GHz base frequency, up to X.X GHz with Intel® Turbo Boost Technology, X MB cache, 8 cores)^{1,2,3,4,5,6}

11th Generation Intel® Core™ i7-11850H vPro® with Intel® Iris® Xe Graphics (X.X GHz base frequency, up to X.X GHz with Intel® Turbo Boost Technology, X MB cache, 8 cores)^{1,2,3,4,5,6}

11th Generation Intel® Core™ i7 11800H with Intel® Iris® Xe Graphics (X.X GHz base frequency, up to X.X GHz with Intel® Turbo Boost Technology, X MB cache, 8 cores)^{1,2,3,4,5}

11th Generation Intel® Core™ i5-11500H vPro® with Intel® Iris® Xe Graphics (X.X GHz base frequency, up to X.X GHz with Intel® Turbo Boost Technology, X MB cache, 6 cores)^{1,2,3,4,5,6}

11th Generation Intel® Core™ i5 11400H with Intel® Iris® Xe Graphics (X.X GHz base frequency, up to X.X GHz with Intel® Turbo Boost Technology, X MB cache, 6 cores)^{1,2,3,4,5,6}

¹ Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

² Processor speed denotes maximum performance mode; processors will run at lower speeds in battery optimization mode.

³ Intel Turbo Boost performance varies depending on hardware, software and overall system configuration. Energy Efficient Turbo is a power management feature that can lower the maximum core ratio (frequency), if the CPU thinks it can achieve about the same performance as with the maximum turbo frequency. Energy Efficient Turbo feature is disabled in Comet Lake H in order to prioritize performance in DC mode. It can be changed in F10 BIOS settings. See www.intel.com/technology/turboboost for more information.

⁴ In accordance with Microsoft's support policy, HP does not support the Windows 8 or Windows 7 operating system on products configured with Intel and AMD 7th generation and forward processors or provide any Windows 8 or Windows 7 drivers on <http://www.support.hp.com>.

⁵ For full Intel® vPro® functionality, Windows 10 Pro 64 bit, a vPro supported processor, vPro enabled chipset, vPro enabled wired LAN and/or WLAN card and TPM 2.0 are required. Some functionality requires additional 3rd party software in order to run. See <http://intel.com/vpro>

⁶ Intel® Iris® Xe Graphics capabilities require system to be configured with Intel® Core™ i5 or i7 processors and dual channel memory. Intel® Iris® Xe Graphics with Intel® Core™ i5 or i7 processors and single channel memory will only function as UHD graphics.

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Features

CHIPSET

? Mobile Intel® TigerLake PCH-H, WM 590

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INTEL® CORE™ I5 WITH VPRO/CORE I7 WITH VPRO TECHNOLOGY CAPABLE

? Intel® Core™ i5 with vPro, Core™ i7 with vPro and Core™ i9 with vPro technology is a selectable feature that is available on units configured with select processors, a qualified Intel® WLAN module and a preinstalled Windows® operating system. It provides advances in remote manageability, security, energy efficient performance, and wireless connectivity. Intel® Active Management Technology (iAMT) offers built-in manageability and proactive security for networked mobile workstations, even when they are powered off* or when the operating system is inoperable. It can help identify threats before they reach the network, isolate infected systems, and update regardless of their power state.^{1,2}

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¹ Requires a Windows operating system, network hardware and software, connection with a power source, and a direct (non-VP corporate network connection which is either cable or wireless LAN.

² For full Intel® vPro functionality, Windows 10 Pro 64 bit, a vPro supported processor, vPro enabled chipset, vPro enabled wire LAN and/or WLAN card and TPM 2.0 are required. Some functionality requires additional 3rd party software in order to run. See <http://intel.com/vpro>

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GRAPHICS

? Integrated

? Intel® Iris® Xe Graphics^{1,2,3,4,5}

? Discrete

? NVIDIA Graphic options:

? NVIDIA RTX™ A2000 (4 GB GDDR6 dedicated)^{1,2,3,4,5}

? NVIDIA RTX™ T1200 (4 GB GDDR6 dedicated)^{1,2,3,4,5}

? NVIDIA RTX™ T600 (4 GB GDDR6 dedicated)^{1,2,3,4,5}

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¹ UHD content required to view UHD images.

² Support HD decode, DX11, DX12, HDMI 1.4, HDCP 2.3 via DP up to 4K @ 60Hz and via HDMI up to 4K @ 30Hz

³ HDMI cable Sold Separately

⁴ Shared video memory (UMA) uses part of the total system memory for video performance. System memory dedicated to video performance is not available for other use by other programs.

⁵ GPU configurations may be limited to specific panel options

Multi Display Support

With HP Thunderbolt™ Dock G2

HP ZBook Power configuration with hybrid graphics supports a maximum of three independent displays which can include any combination of the Internal panel and two external display connected to the HDMI port and/or external displays connected to the dock Type-C, or VGA, or two DisplayPort™ ports.

NOTE: Resolutions are dependent upon monitor capability and resolution and color depth settings.

Without HP Thunderbolt™ Dock G2

HP ZBook Power with hybrid graphics and without the use of the dock supports up to a maximum of three independent displays,

Features

Internal panel plus two external displays connected to the two following ports: HDMI 2.0, Thunderbolt™ 4

NOTE: Resolutions are dependent upon monitor capability and resolution and color depth settings.

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DISPLAY

? Non-touch

- 15.6" diagonal FHD IPS eDP1.2 anti-glare bent WLED-backlit and ambient light sensor 250 nits 45% NTSC (1920 x 1080) ^{1,2}
- 15.6" diagonal FHD Low Power IPS eDP1.4 + PSR2 anti-glare bent WLED-backlit and ambient light sensor 400 nits 100% sRGB (1920 x 1080) ^{1,2}
- 15.6" diagonal UHD Low Power IPS eDP 1.4 + PSR2 +PSR anti-glare bent WLED-backlit and ambient light sensor 400 nits 100% sRGB (3840 x 2160) ^{1,2?}

Touch

- 15.6" diagonal FHD IPS eDP1.2 anti-glare bent WLED-backlit Touch On Cell screen with ambient light sensor 250 nits 45% NTSC (1920 x 1080) ^{1,2,3?}

¹ UHD content required to view UHD images.

² Resolutions are dependent upon monitor capability, and resolution and color depth settings.

³ Actual brightness will be lower with Sure View or touchscreen.

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STORAGE AND DRIVES*

? Max Storage

4TB through two M.2 NVMe drives

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(up to 2) M.2 Storage (NVMe™ PCIe SSD)

256 GB PCIeR NVMe™ M.2 SSD

512 GB PCIeR NVMe™ M.2 SSD

1 TB PCIeR NVMe™ M.2 SSD

2 TB PCIeR NVMe™ M.2 SSD

256 GB PCIeR NVMe™ M.2 SED SSD

512 GB PCIeR NVMe™ M.2 SED SSD

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* For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. ?Up to 35GB of disk is reserved for system recovery software.

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DRIVE CONTROLLERS

? M.2 Storage Bay (PCIe NVMe) Primary slot

Up to PCIe Gen 4 x 4 lanes NVMe Solid State Drive

M.2 Storage Bay (PCIe NVMe) Secondary slot

PCIe Gen 3 x 4 lanes NVMe Solid State Drive

RAID:

RAID 0/1

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Features

MEMORY

? **Maximum Memory¹**

64 GB DDR4-3200 non-ECC SDRAM²

2 DDR4 SODIMMS⁴

Supports Dual Channel Memory³

Slots are customer accessible / upgradeable

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¹ Due to the non-industry standard nature of some third-party memory modules, we recommend HP branded memory to ensure compatibility. If you mix memory speeds, the system will perform at the lower memory speed.

² Transfer rates up to 3200 MT/s on nECC memory.

³ Maximized dual-channel performance requires SODIMMs of the same size and speed in both memory channels.

⁴ Maximum memory capacities assume Windows 64-bit operating systems. With Windows 32-bit operating systems, memory above 3 GB may not all be available due to system resource requirements.

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NETWORKING/COMMUNICATIONS

? **LAN**

Intel® I219-LM GbE, vProR

Intel® I219-V GbE, non-vProR

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? ¹GbE - The term "10/100/1000" or "Gigabit" Ethernet indicates compatibility with IEEE standard 802.3ab for Gigabit Ethernet, and does not connote actual operating speed of 1 Gb/s. For high-speed transmission, connection to a Gigabit Ethernet server and network infrastructure is required.

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WLAN

Intel® Wi-Fi 6 AX201 (2x2) and Bluetooth® 5.2 combo, vProR ¹

Intel® Wi-Fi 6 AX201 (2x2) and Bluetooth® 5.2 combo, non-vProR ¹

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¹ Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 (802.11ax) is backwards compatible with prior 802.11 specs. The specifications for Wi-Fi 6 are draft specifications and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ax WLAN devices. Only available in countries where 802.11ax is supported.

Optional Near Field Communication (NFC) module

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Features

AUDIO/MULTIMEDIA

? Audio

HP Audio, dual stereo speakers, dual array digital microphone³, functions keys for volume up and down, combo microphone/headphone jack, HD audio

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Camera^{1,2}

720p HD webcam with IR

720p HD webcam

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¹ HD content required to view HD images respectively.

² Windows Hello face authentication utilizes a camera specially configured for near infrared (IR) imaging to authenticate and unlock Windows devices as well as unlock your Microsoft Passport.

³Dual-microphone array when equipped with optional webcam.

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KEYBOARDS/POINTING DEVICES/BUTTONS & FUNCTION KEYS

? Keyboard

HP Premium Quiet Keyboard, full-size, spill-resistant, backlit, with Programmable Key, with sperate numeric keypad, clickpad with glass surface, multi-touch gestures and taps enabled

Pointing Devices

Clickpad with multi-touch gestures enabled, taps enabled as default;

Microsoft Precision Touchpad Default Gestures Support

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SOFTWARE AND SECURITY

? Workstation ISV Certifications

See the latest list of certifications at: <http://www.hp.com/go/isv>

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HP ZCENTRAL REMOTE BOOST SOFTWARE

The remote desktop solution for serious workstation users and their most demanding applications. Download at:

<http://www.hp.com/go/RGS>

HP Performance Advisor

HP Performance Advisor enables optimal configuration of HP Mobile Workstations delivering stability and best performance. HP Performance Advisor will guide your system setup allowing a "custom" configuration that best matches the workstation to use requirements. Download at: <http://www.hp.com/go/performanceadvisor>

Software

Adobe Creative Cloud Bundle

Bing search for IE11;

Buy Office;

Data Science Stack

HP Connection Optimizer¹

HP Cloud Recovery²

HP Easy Clean

HP PC Hardware Diagnostics

HP Privacy Settings

HP Hotkey Support;

HP Noise Cancellation Software;

HP Performance Advisor;

Features

HP QuickDrop³
HP Remote Graphics Software;
HP Smart Support⁴
HP Support Assistant;
HP ZCentral Remote Boost 2020 Software for Z workstation⁵
TileApp
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Manageability Features

HP Driver Packs (download)
HP Manageability Integration Kit Gen4 (download)⁶
HP Client Catalog (download)
HP Client Management Script Library (download)
HP Image Assistant (download)
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Security Management

HP Pro Security Edition (optional)⁷
HP Client Security Manager Gen7
HP Sure Sense⁸
HP Sure Click⁹
HP Sure Run Gen4¹⁰
HP Sure Recover Gen4¹¹
HP Sure Start Gen6¹²
HP Sure Admin¹³
HP BIOSphere Gen6¹⁴
HP Secure Erase¹⁵
Absolute Persistence Module¹⁶
HP Drive Lock & Automatic Drive Lock¹⁷
BIOS Update via Network
HP Wake on WLAN
TPM 2.0 Embedded Security Chip (Common Criteria EAL4+ Certified) (FIPS 140-2 Level 2 Certified)¹⁸
HP Fingerprint Sensor
Secured-Core PC Enable¹⁹
HP Tamper Lock
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BIOS Version
ISO/IEC 19678: 2015 (formerly NIST 800-147) compliant
UEFI version: 2.7
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For more information on HP Client Security Software Suite, refer to <http://www.hp.com/go/clientsecurity>.

¹ HP Connection Optimizer requires Windows 10.

² HP Cloud Recovery is available for Z by HP, HP Elite and Pro desktops and laptops PCs with Intel® or AMD processors and requires an open, wired network connection. Note: You must back up important files, data, photos, videos, etc. before use to avoid loss of data. Detail please refer to: <https://support.hp.com/us-en/document/c05115630>

³ HP QuickDrop requires Internet access and Windows 10 PC preinstalled with HP QuickDrop app and either an Android device (phone or tablet) running Android 7 or higher with the Android HP QuickDrop app, and /or an iOS device (phone or tablet) running iOS 12 or higher with the iOS HP QuickDrop app.

⁴ HP Smart Support is available to commercial customers through your HP Service Representative and HP Factory Configuration Services; or it can be downloaded at: <http://www.hp.com/smart-support>. HP Smart Support automatically collects the telemetry necessary upon initial boot of the product to deliver device-level configuration data and health insights.

⁵ HP ZCentral Remote Boost Sender does not come preinstalled on Z Workstations but can be downloaded and run on all Z desktop and laptops without license purchase. With non-Z sender devices, purchase of perpetual individual license or perpetual floating license per simultaneously executing versions and purchase of ZCentral Remote Boost Software Support is required. ZCentral Remote Boost Sender for non-Z Hardware requires a license and Windows 10, RHEL/CentOS (7 or 8), or UBUNTU 18.04 or 20.04 LTS operating systems. macOS (10.14 or newer) operating system and ThinPro 7 are only supported on the receiver side. Requires network access. The software is available for download at <http.com/ZCentralRemoteBoost>.

⁶ HP Manageability Integration Kit can be downloaded from <http://www.hp.com/go/clientmanagement>.

⁷ HP Wolf Pro Security Edition (including HP Sure Click Pro and HP Sure Sense Pro) is available preloaded on select SKUs and, depending on the HP product purchased, includes a paid 1-year or 3-year license. The HP Wolf Pro Security Edition software is licensed under the license terms of the HP Wolf Security Software - End-User license Agreement (EULA) that can be found at: <https://support.hp.com/us-en/document/c00581401?openCLC=true> as that EULA is modified by the following: "7. Term. Unless otherwise terminated earlier pursuant

Features

to the terms contained in this EULA, the license for the HP Wolf Pro Security Edition (HP Sure Sense Pro and HP Sure Click Pro) is effective upon activation and will continue for either a twelve (12) month or thirty-six (36) month license term ("Initial Term"?). At the end of the Initial Term you may either (a) purchase a renewal license for the HP Wolf Pro Security Edition from HP.com, HP Sales or an HP Channel Partner, or (b) continue using the standard versions of HP Sure Click and HP Sure Sense at no additional cost with no future software updates or HP Support."

⁸ HP Sure Sense is available on select HP PCs and is not available with Windows 10 Home.

⁹ HP Sure Click requires Windows 10. See https://bit.ly/2PrLT6A_SureClick for complete details.

¹⁰ HP Sure Run Gen4 is available on select HP PCs and requires Windows 10.

¹¹ HP Sure Recover Gen4 is available on select HP PCs and requires Windows 10 and an open network connection. You must back up important files, data, photos, videos, etc. before using HP Sure Recover to avoid loss of data. Network based recovery using Wi-Fi is only available on PCs with Intel Wi-Fi Module.

¹² HP Sure Start Gen6 is available on select HP PCs.

¹³ HP Sure Admin requires HP Manageability Integration Kit from <http://www.hp.com/go/clientmanagement> and HP Sure Admin Local Access Authenticator smartphone app from the Android or Apple store.

¹⁴ HP BIOSphere Gen6 features may vary depending on the platform and configuration.

¹⁵ For the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "Clear" sanitation method. HP Secure Erase does not support platforms with Intel Optane™.

¹⁶ Absolute firmware module is shipped turned off and can only be activated with the purchase a license subscription and full activation of the software agent.? License subscriptions can be purchased for terms ranging multiple years.? Service is limited, check with Absolute for availability outside the U.S.? Certain conditions apply.? For full details visit: [https://www.absolute.com/about/legal/agreements/absolute/.](https://www.absolute.com/about/legal/agreements/absolute/)

¹⁷ Drive Lock is not supported on NVMe drives

¹⁸ TPM 2.0 is limited on HP ThinPro/HP Smart Zero, and functionality is dependent upon use of a customer-enabled application that can locate the TPM chip.

¹⁹ Secured-Core PC Enable only available with vPro config and with TPM)

POWER

? Power Supply

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Up to 12 hours¹

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HP Long Life 6-cell, 83 Wh Li-ion polymer^{2,5}

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120 W Slim Smart external AC power adapter³

150 W Slim Smart external AC power adapter⁴

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Supports battery fast charge: approximately 50% in 30 minutes (defined under system hibernation and off mode)

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¹ Battery life will vary depending on the product model, configuration, loaded applications, features, use, wireless functionality and power management settings. The maximum capacity of the battery will naturally decrease with time and usage. See MobileMark18 battery benchmark <https://bapco.com/products/mobilemark-2018/> for additional details.

² Battery is internal and not replaceable by customer. Serviceable by warranty. Batteries have a default one year limited warranty except for Long Life batteries which will have same 1-year or 3-year.

³ Only available with UMA graphics

⁴ Only available with discrete graphic options

⁵ Actual battery Watt-hours (Wh) will vary from design capacity. Battery capacity will naturally decrease with shelf life, time, usage, environment, temperature, system configuration, loaded apps, features, power management settings and other factors.

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ENVIRONMENTAL

? Targeting ENERGY STARR certified and EPEATR GOLD registered configurations available ¹

Low halogen²

¹ Based on US EPEATR registration according to IEEE 1680.1-2018 EPEATR. Status varies by country. Visit www.epeat.net for more information.

² External power supplies, power cords, cables and peripherals are not low halogen. Service parts obtained after purchase may not be low halogen.

Features

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WEIGHTS & DIMENSIONS

Dimensions (w x d x h)

35.94 x 23.39 x 2.28 cm

14.15 x 9.21 x 0.9 in

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Weights

Starting at 1.9kg (4.16 lb)

? Weight varies by configuration and components.

A deck: Anodized Aluminum

B deck: PC-ABS with Talc

C deck: Anodized Aluminum

D deck: Anodized Aluminum

Metal Alloy Hinges

PORTS/SLOTS

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Left side

1 RJ-45

1 SuperSpeed USB Type-A 5Gbps signaling rate (charging) [USB 3.1 Gen 1 Type A charging]

1 HDMI^{1,2}

1 smart card reader

1 Nano Security Lock Slot

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Right side

1 power connector

1 Audio Combo Jack

1 USB Type-CR (Thunderbolt™ 4, pass through support DisplayPort™ 1.4, USB 3.1 Gen 2, with BC 1.2)

2 SuperSpeed USB Type-A 5Gbps signaling rate [USB 3.1 Gen 1 Type A]

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¹HDMI port-cable not included.

²HDMI 2.0 with discrete, 1.4 with UMA.

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SERVICE AND SUPPORT

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HP Services offers 3-year and 1-year limited warranties and 90 day software limited warranty options depending on country. Batteries have a default one year limited warranty except for Long Life batteries which will have same 1-year or 3-year limited warranty as the platform. Refer to <http://www.hp.com/support/batterywarranty/> for additional battery information. On-site service and extended coverage is also available. HP Care Pack Services¹ are optional extended service contracts that go beyond the standard limited warranties. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at: <http://www.hp.com/go/cpc>.

¹ HP Care Packs are sold separately. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit www.hp.com/go/cpc. HP Services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.

Technical Specifications ; V System Unit

SYSTEM UNIT

Stand-Alone Power Requirements (AC Power)	Nominal Operating Voltage	19.5V		
	Average Operating Power(idle)	2.5W	System in idle mode + max panel brightness	Adapter Safety test condition
		?	?	?
	Discrete Graphics	NVIDIAR T600: 25W NVIDIAR T1200: Max-Q 35W NVIDIA RTX™ A2000: Max-Q 35W		
	Max Operating Power	<150W		
Temperature	Operating	32°F to 95°F (0°C to 35°C) (Not Writing Optical)		
	Non-operating	-4°F to 140°F (-20°C to 60°C) (writing optical)		
Relative Humidity	Operating	10% to 90%, non-condensing		
	Non-operating	5% to 95%		
Shock	Operating	40 G, 2 ms, half-sine		
	Non-operating	240 G, 2 ms, half-sine		
Random Vibration	Operating	Nominal 1.043 grms		
	Non-operating	Nominal 3.50 grms		
Maximum Altitude (unpressurized)	Operating	-50 to 10,000 ft (-15.24 to 3,048 m)		
	Non-operating	-50 to 40,000 ft (-15.24 to 12,192 m)		
Planned Industry Standard Certifications	UL	Yes		
	CSA	Yes		
	FCC Compliance	Yes		
	ENERGY STARR	Yes		
	EPEATR	Yes ²		
	ICES	Yes		
	Australia / NZ A-Tick Compliance	Yes		
	CCC	Yes		
	Japan VCCI Compliance	Yes		
	KCC	Yes		
	BSMI	Yes		
	CE Marking Compliance	Yes		
	MIL STD 810H	Yes		
	BNCI or BELUS	Yes		
	GOST	Yes		
Saudi Arabian Compliance (ICCP)	Yes			
UKRSERTCOMPUTER	Yes			

¹Configurations of the HP ZBook Power G8 Mobile Workstation that are ENERGY STARR qualified are identified as HP ZBook Power G8 Mobile Workstation ENERGY STAR on HP websites and on <http://www.energystar.gov>.

²Based on US EPEATR registration according to IEEE 1680.1-2018 EPEATR. Status varies by country. Visit www.epeat.net for more information.

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Technical Specifications ; V Displays

DISPLAYS

15.6" diagonal FHD IPS eDP anti-glare bent WLED-backlit and ambient light sensor 250 nits 45% NTSC (1920 x 1080) NWBZ

Outline Dimensions (W x H)	350.96 x 205.54 mm (max)	
Active Area	344.16 x 193.59 mm (typ.)	
Weight	370 g (max)	
Diagonal Size	15.6 inch	
Thickness	3.0 mm/ 5.0 mm (w/PCB) (max)	
Interface	eDP 1.2 (2 lane)	
Panel Technology	IPS	
Surface Treatment	Anti-Glare	
Touch Enabled	No	
Contrast Ratio	600:1 (typ.)	
Refresh Rate	60 hz	
Brightness	250 nits	
Pixel Resolution	Format	1920 x 1080 (FHD)
	Configuration	RGB Stripe
Backlight	LED	
PPI	142	
Color Gamut Coverage	NTSC 45%	
Color Depth	6 bits (Hi FRC supportive w/ condition to enable)	
Viewing Angle	UWVA 85/85/85/85	

NOTE: All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

15.6" diagonal FHD Low Power IPS eDP1.4 anti-glare bent WLED-backlit and ambient light sensor 400 nits low power 100% sRGB (1920 x 1080)

Outline Dimensions (W x H)	349.46 x 204.79 mm (max)	
Active Area	344.16 x 193.59 mm (typ.)	
Weight	325 g (max)	
Diagonal Size	15.6 inch	
Thickness	2.6mm / 4.6mm (PCB) (max)	
Interface	eDP 1.4 (2 lane)	
Panel Technology	IPS	
Surface Treatment	Anti-Glare	
Touch Enabled	No	
Contrast Ratio	1200:1 (typ.)	
Refresh Rate	60 Hz	
Brightness	400 nits	
Pixel Resolution	Format	1920 x 1080 (FHD)
	Configuration	RGB Stripe
Backlight	LED	
PPI	166	

Technical Specifications ; V Displays

Color Gamut Coverage	sRGB 100%
Color Depth	8 bit
Viewing Angle	UWVA 85/85/85/85

NOTE: All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

15.6" diagonal UHD Low Power IPS eDP1.4 +PSR anti-glare bent WLED-backlit and ambient light sensor 400 nits 100% sRGB (3840 x 2160)

Outline Dimensions (W x H)	349.52 x 205.42 mm (max)	
Active Area	344.22 x 193.62 mm (typ.)	
Weight	320 g (max)	
Diagonal Size	15.6"?	
Thickness	2.6mm / 4.6mm (PCB) (max)	
Interface	eDP 1.4 (2 lane)	
Panel Technology	IPS	
Surface Treatment	Anti-glare (AG)	
Touch Enabled	No	
Contrast Ratio	1200:1 (typ.)	
Refresh Rate	60Hz	
Brightness	400nits	
Pixel Resolution	Format	3840x2160 (UHD)
Backlight	LED	
PPI	282	
Color Gamut Coverage	100% sRGB	
Color Depth	8 bits	
Viewing Angle	UWVA 85/85/85/85	

NOTE: All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

15.6" diagonal FHD IPS eDP anti-glare bent WLED-backlit Touch On Panel screen with CorningR GorillaR Glass 5 with ambient light sensor 250 nits 45% NTSC (1920 x 1080)

Outline Dimensions (W x H)	350.96 x 205.74 mm (max)	
Active Area	344.16 x 193.59 mm (typ.)	
Weight	380 g (max)	
Diagonal Size	15.6 inch	
Thickness	3.2mm/ 5.2mm (PCB) (max)	
Interface	eDP 1.2 (2 lane)	
Panel Technology	IPS	
Surface Treatment	Anti-Glare On-cell	
Touch Enabled	Yes	
Contrast Ratio	600:1 (typ.)	
Refresh Rate	60 Hz	
Brightness	250 nits*	
Pixel Resolution	Format	1920 x 1080 (FHD)
	Configuration	RGB Stripe

Technical Specifications ; V Displays

Backlight	LED
PPI	142
Color Gamut Coverage	NTSC 45%
Color Depth	6 bits
Viewing Angle	UWVA 85/85/85/85

NOTE: All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.
*Actual brightness will be lower with Sure View or touchscreen.

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Technical Specifications ; V Storage

STORAGE AND DRIVES

256GB PCIe NVMe TLC M.2 2280 Solid State Drive	Form Factor	M.2 2280		
	Drive Weight	0.02 lb (10 g)		
	Capacity	256GB		
	NAND Type	TLC		
	Height	0.09 in (2.3 mm)		
	Width	0.87 in (22 mm)		
	Interface	PCIe NVMe Gen3X4		
	Performance	Maximum Sequential Read	Maximum Sequential Write	
		3500 MB/s	2200 MB/s	
	Logical Blocks	500,118,192		
	Operating Temperature	32°C to 158°F (0°C to 70°C) [ambient temp]		
	Features	ATA Security; TRIM; L1.2		
	?	For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10) is reserved for system recovery software. Slot 1 supports up to Gen 4 speeds, slot 2 supports up to Gen 3 speeds		

256GB PCIe NVMe TLC M.2 2280 SED Opal 2 Solid State Drive	Form Factor	M.2 2280		
	Drive Weight	0.02 lb (10 g)		
	Capacity	256 GB		
	NAND Type	TLC		
	Height	0.09 in (2.3 mm)		
	Width	0.87 in (22 mm)		
	Interface	PCIe NVMe Gen3X4		
	Performance	Maximum Sequential Read	Maximum Sequential Write	?
		3500 MB/s	2200 MB/s	?
	Logical Blocks	500,118,192		
	Operating Temperature	32°C to 158°F (0°C to 70°C) [ambient temp]		
	Features	ATA Security (Option); TCG Opal 2.0; TRIM; L1.2		
	?	For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10) is reserved for system recovery software. Slot 1 supports up to Gen 4 speeds, slot 2 supports up to Gen 3 speeds		

Technical Specifications ; V Storage

512GB PCIe NVMe TLC M.2 2280 Solid State Drive	Form Factor	M.2 2280		
	Drive Weight	0.02 lb (10 g)		
	Capacity	512GB		
	NAND Type	TLC		
	Height	0.09 in (2.3 mm)		
	Width	0.87 in (22 mm)		
	Interface	PCIe NVMe Gen3X4		
	Performance	Maximum Sequential Read	Maximum Sequential Write	?
		3500 MB/s	2956 MB/s	?
	Logical Blocks	1,000,215,215		
	Operating Temperature	32°C to 158°F (0°C to 70°C) [ambient temp]		
	Features	ATA Security; TRIM; L1.2		
	?	<p>For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10) is reserved for system recovery software.</p> <p>Slot 1 supports up to Gen 4 speeds, slot 2 supports up to Gen 3 speeds</p>		

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512TB PCIe NVMe TLC M.2 2280 SED Opal 2 Solid State Drive	Form Factor	M.2 2280		
	Drive Weight	0.02 lb (10 g)		
	Capacity	512GB		
	NAND Type	TLC		
	Height	0.09 in (2.3 mm)		
	Width	0.87 in (22 mm)		
	Interface	PCIe NVMe Gen3X4		
	Performance	Maximum Sequential Read	Maximum Sequential Write	?
		3500 MB/s	2956 MB/s	?
	Logical Blocks	1,000,215,215		
	Operating Temperature	32°C to 158°F (0°C to 70°C) [ambient temp]		
	Features	ATA Security (Option); TCG Opal 2.0; TRIM; L1.2		
	?	<p>For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10) is reserved for system recovery software.</p> <p>Slot 1 supports up to Gen 4 speeds, slot 2 supports up to Gen 3 speeds</p>		

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Technical Specifications ; V Storage

1TB PCIe NVMe TLC M.2 2280 Solid State Drive	Form Factor	M.2 2280		
	Drive Weight	0.02 lb (10 g)		
	Capacity	1TB		
	NAND Type	TLC		
	Height	0.09 in (2.3 mm)		
	Width	0.87 in (22 mm)		
	Interface	PCIe NVMe Gen3X4		
	Performance	Maximum Sequential Read	Maximum Sequential Write	?
		3500 MB/s	3000 MB/s	?
	Logical Blocks	2,000,409,264		
	Operating Temperature	32°C to 158°F (0°C to 70°C) [ambient temp]		
Features	ATA Security; TRIM; L1.2			
?	<p>For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10) is reserved for system recovery software.</p> <p>Slot 1 supports up to Gen 4 speeds, slot 2 supports up to Gen 3 speeds</p>			

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2TB PCIe NVMe TLC M.2 2280 Solid State Drive	Form Factor	M.2 2280		
	Drive Weight	0.02 lb (10 g)		
	Capacity	2TB		
	NAND Type	TLC		
	Height	0.09 in (2.3 mm)		
	Width	0.87 in (22 mm)		
	Interface	PCIe NVMe Gen3X4		
	Performance	Maximum Sequential Read	Maximum Sequential Write	?
		3500 MB/s	3000MB/s	?
	Logical Blocks	3,907,029,168		
	Operating Temperature	32°C to 158°F (0°C to 70°C) [ambient temp]		
Features	ATA Security (Option);TRIM; L1.2			
?	<p>For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10) is reserved for system recovery software.</p> <p>Slot 1 supports up to Gen 4 speeds, slot 2 supports up to Gen 3 speeds</p>			

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Technical Specifications ; V Storage

512TB PCIe Gen 4 NVMe TLC M.2 2280? Solid State Drive	Form Factor	M.2 2280		
	Drive Weight	0.02 lb (10 g)		
	Capacity	512GB		
	NAND Type	TLC		
	Height	0.09 in (2.3 mm)		
	Width	0.87 in (22 mm)		
	Interface	PCIe NVMe Gen4X4		
	Performance	Maximum Sequential Read	Maximum Sequential Write	?
		6600 MB/s	5100 MB/s	?
	Logical Blocks	1,000,215,215		
	Operating Temperature	32°C to 158°F (0°C to 70°C) [ambient temp]		
Features	Pyrite 2.0; TRIM; L1.2			
?	<p>For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10) is reserved for system recovery software.</p> <p>Slot 1 supports up to Gen 4 speeds, slot 2 supports up to Gen 3 speeds</p>			

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1TB PCIe Gen 4 NVMe TLC M.2 2280 Solid State Drive	Form Factor	M.2 2280		
	Drive Weight	0.02 lb (10 g)		
	Capacity	1TB		
	NAND Type	TLC		
	Height	0.09 in (2.3 mm)		
	Width	0.87 in (22 mm)		
	Interface	PCIe NVMe Gen4X4		
	Performance	Maximum Sequential Read	Maximum Sequential Write	?
		7100 MB/s	5200 MB/s	?
	Logical Blocks	2,000,409,264		
	Operating Temperature	32°C to 158°F (0°C to 70°C) [ambient temp]		
Features	Pyrite 2.0; TRIM; L1.2			
?	<p>For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10) is reserved for system recovery software.</p> <p>Slot 1 supports up to Gen 4 speeds, slot 2 supports up to Gen 3 speeds</p>			

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Technical Specifications ; V Storage

2TB PCIe Gen 4 NVMe TLC M.2 2280 Solid State Drive	Form Factor	M.2 2280		
	Drive Weight	0.02 lb (10 g)		
	Capacity	2TB		
	NAND Type	TLC		
	Height	0.09 in (2.3 mm)		
	Width	0.87 in (22 mm)		
	Interface	PCIe NVMe Gen4X4		
	Performance	Maximum Sequential Read	Maximum Sequential Write	?
		7100 MB/s	5200MB/s	?
	Logical Blocks	4,000,797,360		
	Operating Temperature	32°C to 158°F (0°C to 70°C) [ambient temp]		
	Features	Pyrite 2.0; TRIM; L1.2		
	?	For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10) is reserved for system recovery software. Slot 1 supports up to Gen 4 speeds, slot 2 supports up to Gen 3 speeds		

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Technical Specifications ; V Networking

NETWORKING/COMMUNICATION

?

<p>Intel i219LM 10/100/1000? Integrated NIC vProR</p>	<p>Connector</p> <p>System Interface</p> <p>Data Rates Supported</p> <p>IEEE Compliance</p> <p>Performance</p> <p>Power consumption</p> <p>Power Management</p> <p>Management Interface</p> <p>IT Manageability</p> <p>Security & Manageability</p>	<p>RJ-45</p> <p>PCI(Intel proprietary) + SMBus</p> <p>10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14)</p> <p>100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30)</p> <p>1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023 clauses 40)</p> <p>Auto-Negotiation (Automatic Speed Selection)</p> <p>Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100 Mbit/s</p> <p>IEEE 802.1p QoS (Quality of Service) Support</p> <p>IEEE 802.1q VLAN support</p> <p>IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable)</p> <p>IEEE 802.3az EEE (Energy Efficient Ethernet)</p> <p>TCP/IP/UDP Checksum Offload (configurable)</p> <p>Protocol Offload (ARP & NS)</p> <p>Large send offload and Giant send offload</p> <p>Receiving Side Scaling(Hash Mode Only)</p> <p>Jumbo Frame 9K</p> <p>Cable Disconnection: 25mW</p> <p>100Mbps Full Run: 450mW</p> <p>1000bp Full Run: 1000mW</p> <p>WoL Enable(S3/S4/S5): 50mW</p> <p>WoL Disable(S3/S4/S5): 25mW</p> <p>ACPI compliant - multiple power modes</p> <p>Situation-sensitive features reduce power consumption</p> <p>Advanced link down power saving for reducing link down power consumption</p> <p>Auto MDI/MDIX Crossover cable detection</p> <p>Wake-on-LAN from modem standby or sleep state (Magic Packet and Microsoft Wake-Up Frame); Wake-on-LAN from off (Magic Packet only)</p> <p>PXE 2.1 Remote Boot</p> <p>Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30))</p> <p>Comprehensive diagnostic and configuration software suite</p> <p>Virtual Cable Doctor for Ethernet cable status</p> <p>IntelR vPro™ support with appropriate IntelR chipset components</p>
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Technical Specifications ; V Networking

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<p>Intel i219v 10/100/1000 Integrated NIC non-vProR</p>	<p>Connector</p> <p>System Interface</p> <p>Data Rates Supported</p> <p>IEEE Compliance</p> <p>Performance</p> <p>Power consumption</p> <p>Power Management</p> <p>Management Interface</p> <p>IT Manageability</p>	<p>RJ-45</p> <p>PCI(Intel proprietary) + SMBus</p> <p>10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14)</p> <p>100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30)</p> <p>1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023 clauses 40)</p> <p>Auto-Negotiation (Automatic Speed Selection)</p> <p>Full Duplex Operation at all Speeds, Half Duplex operation at 10, 100 & 1000 Mbit/s</p> <p>IEEE 802.1p QoS (Quality of Service) Support</p> <p>IEEE 802.1q VLAN support</p> <p>IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable)</p> <p>IEEE 802.3az EEE (Energy Efficient Ethernet)</p> <p>IEEE 802.3i 10BASE-T</p> <p>IEEE 802.3u 100BASE-TX</p> <p>IEEE 802.3ab 1000BAE-T</p> <p>IEEE 802.3bz 2.5GBASE-T</p> <p>TCP/IP/UDP Checksum Offload (configurable)</p> <p>Protocol Offload (ARP & NS)</p> <p>Large send offload and Giant send offload</p> <p>Receiving Side Scaling(Hash Mode only)</p> <p>Jumbo Frame 9K</p> <p>Cable Disconnection: 25mW</p> <p>100Mbps Full Run: 450mW</p> <p>1000bp Full Run: 1000mW</p> <p>WoL Enable(S3/S4/S5): 50mW</p> <p>WoL Disable(S3/S4/S5): 25mW</p> <p>ACPI compliant - multiple power modes</p> <p>Situation-sensitive features reduce power consumption</p> <p>Advanced link down power saving for reducing link down power consumption</p> <p>Auto MDI/MDIX Crossover cable detection</p> <p>Wake-on-LAN from modern standby or sleep state (Magic Packet and Microsoft Wake-Up Frame); Wake-on-LAN from off (Magic Packet only)</p> <p>PXE 2.1 Remote Boot</p> <p>Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30))</p> <p>Comprehensive diagnostic and configuration software suite</p> <p>Virtual Cable Doctor for Ethernet cable status</p>
<p>?</p>	<p>?</p>	<p>?</p>

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Intel Wi-Fi 6 AX201 + BT5.2 **Wire**

Technical Specifications ; V Networking

(802.11ax 2x2, non-vProR, supporting gigabit file transfer speeds*) non-vProR**

less IEEE 802.11b
LAN IEEE 802.11g
Stan IEEE 802.11n
dard IEEE 802.11ac
s IEEE 802.11ax
 IEEE 802.11d
 IEEE 802.11e
 IEEE 802.11h
 IEEE 802.11i
 IEEE 802.11k
 IEEE 802.11r
 IEEE 802.11v

Inte
rope
rabil
ity Wi-Fi certified

Freq 802.11b/g/n/ax
uenc 2.402 - 2.482 GHz
y 802.11a/n/ac/ax
Ban 4.9 - 4.95 GHz (Japan)
d 5.15 - 5.25 GHz
 5.25 - 5.35 GHz
 5.47 - 5.725 GHz
 5.825 - 5.850 GHz

Data 802.11b: 1, 2, 5.5, 11 Mbps
Rate 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
s 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)
 802.11ac : MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, ,80MHz & 160MHz)
 802.11ax : MCS0 ~ MCS11, (1SS and 2SS) (20MHz, 40MHz, ,80MHz & 160MHz)

Mod
ulati Direct Sequence Spread Spectrum
on OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM

Secu IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only
rity¹ AES-CCMP: 128 bit in hardware
 802.1x authentication
 WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.
 WPA3 certification
 IEEE 802.11i
 WAPI

Net
wor
k
Arch
itect
ure
Mod Ad-hoc (Peer to Peer)
els Infrastructure (Access Point Required)

Roa
min
g IEEE 802.11 compliant roaming between access points
Outp 802.11b : +18.5dBm minimum
ut 802.11g : +17.5dBm minimum

Technical Specifications ; V Networking

Power²

- 802.11a : +18.5dBm minimum
- 802.11n HT20(2.4GHz) : +15.5dBm minimum
- 802.11n HT40(2.4GHz) : +14.5dBm minimum
- 802.11n HT20(5GHz) : +15.5dBm minimum
- 802.11n HT40(5GHz) : +14.5dBm minimum
- 802.11ac VHT80(5GHz) : +11.5dBm minimum
- 802.11ac VHT160(5GHz) : +11.5dBm minimum
- 802.11ax HT40(2.4GHz) : +10dBm minimum
- 802.11ax VHT160(5GHz) : +10dBm minimum

Power Consumption

- Transmit mode 2.0 W
- Receive mode 1.6 W
- Idle mode (PSP) 180 mW (WLAN Associated)
- Idle mode 50 mW (WLAN unassociated)
- Connected Standby??? 10mW
- Radio disabled 8 mW

Power Management

- ACPI and PCI Express compliant power management
- 802.11 compliant power saving mode

Management

Receiver Sensitivity³

- 802.11b, 1Mbps : -93.5dBm maximum
- 802.11b, 11Mbps : -84dBm maximum
- 802.11a/g, 6Mbps : -86dBm maximum
- 802.11a/g, 54Mbps : -72dBm maximum
- 802.11n, MCS07 : -67dBm maximum
- 802.11n, MCS15 : -64dBm maximum
- 802.11ac, MCS0 : -84dBm maximum
- 802.11ac, MCS9 : -59dBm maximum
- 802.11ax, MCS11(HT40): -59dBm maximum
- 802.11ax, MCS11(VHT160): -58.5dBm maximum

Antenna Type

- High efficiency antenna with spatial diversity, mounted in the display enclosure
- Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications

Form Factor

- PCI-Express M.2 MiniCard with CNVi Interface

Dimensions

- 1. Type 2230 : 2.3 x 22.0 x 30.0 mm
- 2. Type 1216: 1.67 x 12.0 x 16.0 mm

Weight

- 1. Type 2230 : 2.8g
- 2. Type 126: 1.3g

Operating Voltage

- 3.3v +/- 9%

Temperature

- Operating?? 14°C to 158°C F (-10°C to 70°C C)
- Non-operating -40°C to 176°C F (-40°C to 80°C C)

Technical Specifications ; V Networking

Humidity	Operating? Non-operating?	10% to 90% (non-condensing) 5% to 95% (non-condensing)
Altitude	Operating? Non-operating?	0 to 10,000 ft (3,048 m) 0 to 50,000 ft (15,240 m)
LED Activity	LED Amber? - Radio Off; LED Off - Radio ON	

?

HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0/5.1 Wireless Technology

Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy : 0~79 (1 MHz/CH) BLE : 0~39 (2 MHz/CH)
Data Rates and Throughput	Legacy : 3 Mbps data rate; throughput up to 2.17 Mbps BLE : 1 Mbps data rate; throughput up to 0.2 Mbps Legacy : Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy : Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 9.5 dBm for BR and EDR.
Power Consumption	Peak (Tx): 330 mW Peak (Rx): 230 mW Selective Suspend: 17 mW
Bluetooth Software Supported Link Topology	Microsoft Windows Bluetooth Software
Power Management	Microsoft Windows ACPI, and USB Bus Support
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels? Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 -Link Layer Privacy LE Privacy 1.2 -Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)

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Technical Specifications ; V Networking

*GbE - The term "10/100/1000" or "Gigabit" Ethernet indicates compatibility with IEEE standard 802.3ab for Gigabit Ethernet, and does not connote actual operating speed of 1 Gb/s. For high-speed transmission, connection to a Gigabit Ethernet server and network infrastructure is required.

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**Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 (802.11ax) is backwards compatible with prior 802.11 specs. The specifications for Wi-Fi 6 are draft specifications and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ax WLAN devices. Only available in countries where 802.11ax is supported.

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Intel Wi-Fi 6 AX201 + BT5.2 (802.11ax 2x2, vProR, supporting gigabit file transfer speeds)**

Wireless LAN Standards
 IEEE 802.11a
 IEEE 802.11b
 IEEE 802.11g
 IEEE 802.11n
 IEEE 802.11ac
 IEEE 802.11ax
 IEEE 802.11d
 IEEE 802.11e
 IEEE 802.11h
 IEEE 802.11i
 IEEE 802.11k
 IEEE 802.11r
 IEEE 802.11v

Interoperability
 Wi-Fi certified

Frequency Band
 802.11b/g/n/ax
 2.402 - 2.482 GHz
 802.11a/n/ac/ax
 4.9 - 4.95 GHz (Japan)
 5.15 - 5.25 GHz
 5.25 - 5.35 GHz
 5.47 - 5.725 GHz
 5.825 - 5.850 GHz

Data Rates
 802.11b: 1, 2, 5.5, 11 Mbps
 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)
 802.11ac : MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, ,80MHz & 160MHz)
 802.11ax : MCS0 ~ MCS11, (1SS and 2SS) (20MHz, 40MHz, ,80MHz & 160MHz)

Modulation
 Direct Sequence Spread Spectrum
 OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM

Security¹
 IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only
 AES-CCMP: 128 bit in hardware
 802.1x authentication
 WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.
 WPA3 certification
 IEEE 802.11i
 WAPI

Network

Technical Specifications ; V Networking

Architecture	<p>Mod Ad-hoc (Peer to Peer)</p> <p>els Infrastructure (Access Point Required)</p>
Roaming	IEEE 802.11 compliant roaming between access points
Output Power²	<p>802.11b : +18.5dBm minimum</p> <p>802.11g : +17.5dBm minimum</p> <p>802.11a : +18.5dBm minimum</p> <p>802.11n HT20(2.4GHz) : +15.5dBm minimum</p> <p>802.11n HT40(2.4GHz) : +14.5dBm minimum</p> <p>802.11n HT20(5GHz) : +15.5dBm minimum</p> <p>802.11n HT40(5GHz) : +14.5dBm minimum</p> <p>802.11ac VHT80(5GHz) : +11.5dBm minimum</p> <p>802.11ac VHT160(5GHz) : +11.5dBm minimum</p> <p>802.11ax HT40(2.4GHz) : +10dBm minimum</p> <p>802.11ax VHT160(5GHz) : +10dBm minimum</p>
Power	<p>Transmit mode :2.0 W</p> <p>Receive mode :1.6 W</p>
Consumption	<p>Idle mode (PSP) 180 mW (WLAN Associated)</p> <p>Idle mode :50 mW (WLAN unassociated)</p> <p>Connected Standby/Modern Standby: 10mW</p> <p>Radio disabled: 8 mW</p>
Power Management	<p>ACPI and PCI Express compliant power management</p> <p>802.11 compliant power saving mode</p>
Receiver Sensitivity³	<p>802.11b, 1Mbps : -93.5dBm maximum</p> <p>802.11b, 11Mbps : -84dBm maximum</p> <p>802.11a/g, 6Mbps : -86dBm maximum</p> <p>802.11a/g, 54Mbps : -72dBm maximum</p> <p>802.11n, MCS07 : -67dBm maximum</p> <p>802.11n, MCS15 : -64dBm maximum</p> <p>802.11ac, MCS0 : -84dBm maximum</p> <p>802.11ac, MCS9 : -59dBm maximum</p> <p>802.11ax, MCS11(HT40): -59dBm maximum</p> <p>802.11ax, MCS11(VHT160): -58.5dBm maximum</p>
Antenna Type	<p>High efficiency antenna with spatial diversity, mounted in the display enclosure</p> <p>Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications</p>
Form Factor	PCI-Express M.2 MiniCard with CNVi Interface
Dimensions	<p>1. Type 2230 : 2.3 x 22.0 x 30.0 mm</p> <p>2. Type 1216: 1.67 x 12.0 x 16.0 mm</p>

Technical Specifications ; V Networking

Weight	1. Type 2230 : 2.8g 2. Type 126: 1.3g	
Operating Voltage	3.3v +/- 9%	
Temperature	Operating?? Non-operating	14°CX to 158°CX F (-10°CX to 70°CX C) -40°CX to 176°CX F (-40°CX to 80°CX C)
Humidity	Operating? Non-operating?	10% to 90% (non-condensing) 5% to 95% (non-condensing)
Altitude	Operating? Non-operating	0 to 10,000 ft (3,048 m) 0 to 50,000 ft (15,240 m)

LED Activity LED Amber? - Radio OFF; LED White - Radio ON

?

HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0/5.1/5.2 Wireless Technology

Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy : 0~79 (1 MHz/CH) BLE : 0~39 (2 MHz/CH)
Data Rates and Throughput	Legacy : 3 Mbps data rate; throughput up to 2.17 Mbps BLE : 1 Mbps data rate; throughput up to 0.2 Mbps Legacy : Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy : Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 9.5 dBm for BR and EDR.
Power Consumption	Peak (Tx): 330 mW Peak (Rx): 230 mW Selective Suspend: 17 mW
Bluetooth Software Supported Link Topology	Microsoft Windows Bluetooth Software
Power Management	Microsoft Windows ACPI, and USB Bus Support
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
?	Power Management Certifications
	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark
	Bluetooth Profiles Supported
	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode

Technical Specifications ; V Networking

LE Link Layer
 LE Low Duty Cycle Directed Advertising
 LE L2CAP Connection Oriented Channels?
 Train Nudging & Interlaced Scan
 BT4.2 ESR08 Compliance
 LE Secure Connection- Basic/Full
 LE Privacy 1.2 -Link Layer Privacy
 LE Privacy 1.2 -Extended Scanner Filter Policies
 LE Data Packet Length Extension
 FAX Profile (FAX)
 Basic Imaging Profile (BIP)2
 Headset Profile (HSP)
 Hands Free Profile (HFP)
 Advanced Audio Distribution Profile (A2DP)

? **Security & Manageability** IntelR vProR support with appropriate IntelR chipset components

*GbE - The term "10/100/1000" or "Gigabit" Ethernet indicates compatibility with IEEE standard 802.3ab for Gigabit Ethernet, and does not connote actual operating speed of 1 Gb/s. For high-speed transmission, connection to a Gigabit Ethernet server and network infrastructure is required.

? **Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 (802.11ax) is backwards compatible with prior 802.11 specs. The specifications for Wi-Fi 6 are draft specifications and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ax WLAN devices. Only available in countries where 802.11ax is supported

? **NFC (Near Field Communication) module (optional)**

Dimensions (L x W x H) Module 25 mm by 10 mm by 2.0 mm

Chipset NPC100

System interface I2C

NFC standards ISO/IEC 14443 A
 ISO/IEC 14443 B
 ISO/IEC 15693
 ISO/IEC 18092
 ECMA-340 NFCIP-1 Target and Initiator
 ECMA-320 NFCIP-2

NFC Forum Support Tag Type 1, Type 2, Type3 and Type 4, NFCIP-1 and NFCIP-2

Reader ISO/IEC 14443 A

Technical Specifications ; V Networking

(PC ISO/IEC 14443 B
D- ISO/IEC 15693
VCD MIFARE 1K
) MIFARE 4K
Mod MIFARE DESFire
e(1) FeliCa
Jewel and Topaz cards

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VICC ISO/IEC 14443 A
) ISO/IEC 14443 B and B'
Mod MIFARE
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Technical Specifications ; V Networking

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I/O 1.8V or 3.3V

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Pow Boos VBAT= 3.3V,
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? VCC_ Polling	7.3 mA
BOOS	
T = Detected Test Tag Type 1	Total 283.8 mA Net Module 236.8 mA
5V)	
Mode Detected Test Tag Type 2	Total 288.8 mA Net Module 241.8 mA
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Cons Detected Test Tag Type 3	Total 287.7 mA Net Module 240.7 mA
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Typic Detected Test Tag Type 4	Total 282.3 mA Net Module 235.3 mA
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Ant Antenna connector, 0.5mm pitch, 7 connector FPC.? Antenna matching is external to module.
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Technical Specifications ; V Power

POWER

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120 Dime 138x68.5x25.4mm

Wa nsio

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Sli Weig unit: 350g +/- 10g
m ht

Sm art Inpu **Input Efficiency** 88% at 115 Vac and 89% at 230Vac

AC t **Input frequency range** 47 ~ 63 Hz

Ada pte **Input AC current** 1.7 A at 90 Vac and Maximum Load

r Outp **Output power** 120W

ut **DC output** 19.5V

Hold-up time 5ms at 115 Vac input

Output current limit <18.0A

Conn C5

ecto

r

Envi **Operating** 32oFto 95oF (0oto 35oC)
ron **temperature**

men **Non-operating (storage) temperature** -4oFto 185oF (-20oto 85oC)
tal

Desi **Altitude** 0 to 16,400 ft (0 to 5000m)

gn **Humidity** 5% to 95%

Storage Humidity 5% to 95%

EMI Eg:

and *CE Mark - full compliance with LVD and EMC directives

Safe * Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS,
ty DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE.

Certi * MTBF - over 100,000 hours at 25oC ambient condition.

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NOTE: Can only be configured with Intel UMA Graphics option

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Technical Specifications ; V Power

150 Dime	138x66x22mm	
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Sli Weig	unit: 325g +/- 10g	
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Sm art	Input Efficiency	88% at 115 Vac and 89% at 230Vac
AC t	Input frequency range	47 ~ 63 Hz
Ada	Input AC current	2.7 A at 90 Vac and Maximum Load
pte	Output power	150W
r	DC output	19.5V
	Hold-up time	5ms at 115 Vac input
	Output current limit	<16.0A
Conn	C5	
ecto		
r		
Envi	Operating temperature	32oFto 95oF (0oto 35oC)
ron	Non-operating (storage) temperature	-4oFto 185oF (-20oto 85oC)
men	Altitude	0 to 16,400 ft (0 to 5000m)
tal	Humidity	5% to 95%
Desi	Storage Humidity	5% to 95%
gn		
EMI	Eg:	
and	*CE Mark - full compliance with LVD and EMC directives	
Safe	* Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE.	
ty	* MTBF - over 100,000 hours at 25°C ambient condition.	
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? **NOTE:** Can only be configured with Quadro T1200 and A2000 Graphics option

Technical Specifications ; V Power

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(8 3 Ene Voltage 11.58V

W rgy Amp-hour capacity 7.170Ah

h) Ba Watt-hour capacity 83Wh

tt Te Operating (Charging) 32°C to 113°C F (0°C to 45°C C)

er mp

y* era Operating (Discharging) 14°C to 122°C F (-10°C to 60°C C)

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Wa Refer to <http://www.hp.com/support/batterywarranty/> for battery warranty information.

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NOTE: Batteries have a default one year limited warranty except for Long Life batteries which will have same 1-year or 3-year limited warranty as the platform.

*Actual battery Watt-hours (Wh) will vary from design capacity. Battery capacity will naturally decrease with shelf life, time, usage, environment, temperature, system configuration, loaded apps, features, power management settings and other factors.

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Technical Specifications ; V Environmental

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ENVIRONMENTAL DATA?

E This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks:

- IT ECO declaration
- US ENERGY STARR
- US Federal Energy Management Program (FEMP)
- EPEAT® Gold registered in the United States. See <http://www.epeat.net> for registration status in your country.
- TCO certified?
- China Energy Conservation Program (CECP)
- China State Environmental Protection Administration (SEPA)
- Taiwan Green Mark
- Korea Eco-label
- Japan PC Green label*?

- Ocean-bound plastic in Speaker Enclosure
- 15% post-consumer recycled plastic
- External Power Supply 90% Efficiency
- Low halogen
- Outside Box and corrugated cushions are 100% sustainably sourced and recyclable
- Molded Paper Pulp Cushion inside box is 100% sustainably sourced and recyclable????????????????????
- Bulk packaging available

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The configuration used for the Energy Consumption and Declared Noise Emissions data for the Notebook model is based on a "Typically Configured Notebook"?

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115VAC, 60Hz

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1.43 W

230VAC, 50Hz

6.31 W

1.41 W

1.41 W

100VAC, 50Hz

5.92 W

1.47 W

1.47 W

Technical Specifications ; V Environmental

?	0.41 W	0.42 W	0.42 W
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? ?
NOTE:?

Energy efficiency data listed is for an ENERGY STARR compliant product if offered within the model family. HP computers marked with the ENERGY STARR Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STARR specifications for computers. If a model family does not offer ENERGY STARR compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft WindowsR operating system.

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Technical Specifications ; V Environmental

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5 BTU/hr

5 BTU/hr

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1 BTU/hr

1 BTU/hr

***NOTE:** Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.

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Technical Specifications ; V Environmental

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L "This product can be upgraded, possibly extending its useful life by several years.? Upgradeable features and/or components
o contained in the product may include:

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? Spare parts are available throughout the warranty period and or for up to "5"? years after the end of production.
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- This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive? - 2011/65/EC.
- This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive - 2002/96/EC.
- This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986).
- This product is in compliance with the IEEE 1680 (EPEAT) standard at the Gold level, see www.epeat.net
- Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043.
- This product is 95.5% recycle-able when properly disposed of at end of life.

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External:	PAPER/Corrugated	250 g
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Technical Specifications ; V Environmental

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? Internal:	PAPER/Molded pulp	177 g
?	PLASTIC/Polyethylene low density	10 g

The plastic packaging material contains at least 0% recycled content.

The corrugated paper packaging materials contains at least 45% recycled content.

R HP Inc. complies fully with materials regulations. We were among the first companies to extend the restrictions in the European Union (EU) Restriction of Hazardous Substances (RoHS) Directive to our products worldwide through the HP GSE. HP has contributed to the development of related legislation in Europe, as well as China, India, and Vietnam.

S We believe the RoHS directive and similar laws play an important role in promoting industry-wide elimination of substances of concern. We have supported the inclusion of additional substances-including PVC, BFRs, and certain phthalates-in future RoHS legislation that pertains to electrical and electronics products.

Pl We met our voluntary objective to achieve worldwide compliance with the new EU RoHS requirements for virtually all relevant products by July 2013, and we will continue to extend the scope of the commitment to include further restricted substances as regulations continue to evolve.

e To obtain a copy of the HP RoHS Compliance Statement, see [?HP RoHS position statement](#).

?

M This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment?at http://www.hp.com/hpinfo/globalcitizenship/environment/supplychain/gen_specifications.html):

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- Asbestos
- Certain Azo Colorants
- Certain Brominated Flame Retardants - may not be used as flame retardants in plastics
- Cadmium
- Chlorinated Hydrocarbons
- Chlorinated Paraffins
- Bis(2-Ethylhexyl) phthalate (DEHP)
- Benzyl butyl phthalate (BBP)
- Dibutyl phthalate (DBP)
- Diisobutyl phthalate (DIBP)
- Formaldehyde
- Halogenated Diphenyl Methanes
- Lead carbonates and sulfates
- Lead and Lead compounds
- Mercuric Oxide Batteries
- Nickel - finishes must not be used on the external surface designed to be frequently handled or carried by the user.
- Ozone Depleting Substances
- Polybrominated Biphenyls (PBBs)
- Polybrominated Biphenyl Ethers (PBBEs)
- Polybrominated Biphenyl Oxides (PBBOs)
- Polychlorinated Biphenyl (PCB)
- Polychlorinated Terphenyls (PCT)
- Polyvinyl Chloride (PVC) - except for wires and cables, and certain retail packaging has been voluntarily removed from most applications.
- Radioactive Substances
- Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)

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P HP follows these guidelines to decrease the environmental impact of product packaging:

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Technical Specifications ; V Environmental

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- Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials.
- Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
- Design packaging materials for ease of disassembly.
- Maximize the use of post-consumer recycled content materials in packaging materials.
- Use readily recyclable packaging materials such as paper and corrugated materials.
- Reduce size and weight of packages to improve transportation fuel efficiency.
- Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.

HP offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: <http://www.hp.com/go/reuse-recycle> or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.

The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: <http://www.hp.com/go/recyclers>. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.

For more information about HP's commitment to the environment:?????

Global Citizenship Report

<http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html>

Eco-label certifications

<http://www8.hp.com/us/en/hp-information/environment/ecolabels.html>

ISO 14001 certificates:

<http://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c04755842>

and

<http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf>

Technical Specifications ; V Environmental

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- Percentage of ocean-bound plastic contained in each component varies by product
- Recycled plastic content percentage is based on the definition set in the IEEE 1680.1-2018 standard.
- External power supplies, WWAN modules, power cords, cables and peripherals excluded.
- 100% outer box packaging and corrugated cushions made from sustainably sourced certified and recycled fibers.
- Fiber cushions made from 100% recycled wood fiber and organic materials.

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Options and Accessories (sold separately and availability may vary by country)

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Type	Description	Part #
Displays	HP Z32 31.5"? 4k UHD Display	1AA81A8#XXX
	HP Z38c 37.5"? Curved Display	Z4W65A8#ABA
?	?	?
Cases	HP 17.3 Business Backpack	2SC67AA
	HP 15.6 Business Top Load	2SC66AA
	HP 17.3 Business Slim Top Load	2UW02AA
	HP Prelude Pro Recycle Backpack	1X644AA
	HP Prelude Pro Recycle Top Load	1X645AA
	HP Executive 17.3 Backpack	6KD05AA
	HP Executive 15.6 Top Load	6KD06AA
	HP Executive 15.6 Backpack	6KD07AA
	HP Executive 17.3 Top Load	6KD08AA
	HP Executive 15.6 Leather Top Load	6KD09AA
	HP Prelude 15.6 Top Load	1E7D7AA
	HP Prelude 15.6 Backpack	1E7D6AA
	HP Renew Business 17.3 Laptop Backpack	3E2U5AA
	HP Renew Business 17.3 Laptop Bag	3E2U6AA
	HP Renew Business 15.6 Laptop Bag	3E5F8AA
	?	?
Docking Accessories	HP TB Audio Module (comp with Thunderbolt Dock G2)	3AQ21AA
	?	?
Docking station	HP USB-C Mini Dock - power not supported on mWKS	1PM64AA
	HP TB Dock G2 w/ Combo Cable (this is 230W)	3TR87AA
	HP USB-C/A Universal Dock G2 Power Not Supported on Mobile Workstations	5TW13AA
	HP USB-C Dock G5 Power Not Supported on Mobile Workstations	5TW10AA
	?	?
Input/Output - Mice & Keyboard	HP Comfort Grip Wireless Mouse (See Link 5 Tab)	H2L63AA
	HP USB Travel Mouse	G1K28AA
	HP Wireless Premium Mouse (See Link 5 Tab)	1JR31AA
	HP Wired 320M Mouse	9VA80AA
	HP Travel Bluetooth Mouse	6SP30AA
	HP Multi-Device 635 Black Wireless Mouse	1D0K2AA
	HP Creator 935 Black Wireless Mouse	1D0K8AA
	HP Slim Wireless Keyboard and Mouse	T6L04AA
	HP Wireless (Link-5) Keyboard	T6U20AA

Options and Accessories (sold separately and availability may vary by country)

	HP 320K Wired Keyboard	9SR37AA
?	HP 125 Wired Keyboard	266C9AA
?	HP Wired Desktop 320MK Mouse and Keyboard	9SR36AA
?	?	?
Input/Output - Adapter	HDMI to VGA Adapter	H4F02AA
	HP HDMI to DVI Adapter	F5A28AA
?	HP USB-C to USB 3.0 Adapter	N2Z63AA
?	HP USB-C to DisplayPort Adapter	N9K78AA
?	HP USB-C to VGA Adapter	N9K76AA
?	HP USB 3.0 to Gigabit Adapter	N7P47AA
?	HP USB-C to RJ45 Adapter	V7W66AA
?	HP USB-C to HDMI 2.0 Adapter	1WC36AA
?	?	?
Memory	HP 4GB 3200MHz DDR4 (pending approval)	286H5AA
?	HP 8GB 3200MHz DDR4 (pending approval)	286H8AA
?	HP 16GB 3200MHz DDR4(pending approval)	286J1AA
?	?	?
Power - A/C Adapter	HP 150W Slim Smart 4.5mm AC Adapter	4SC18AA
?	?	?
Security	HP Nano Keyed Cable Lock	1AJ39AA
	HP Sure Key Cable Lock	6UW42AA
?	?	?
Storage - External	HP External USB DVDRW Drive	F2B56AA
?	?	?
Storage - SS M2	HP 256GB PCIe-3x4 NVME M.2 SSD	1D0H6AA
?	HP 512GB PCI-e 3x4 NVMe M2 SSD	1D0H7AA
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Date of change:	Version History:	?	Description of change:
June 29, 2021	From v1 to v2	Changed	AUDIO/MULTIMEDIA section
July 9, 2021	From v2 to v3	Changed	NETWORKING/COMMUNICATIONS section

?